



XFP-10GB-DW39-100-OPC

MSA and TAA 10GBase-DWDM XFP Transceiver C-Band 100GHz (SMF, 1546.12nm, 100km, LC, DOM)

Features

- INF-8077i Compliance
- Duplex LC Connector
- Temperature-stabilized EML transmitter and PIN receiver
- Single-mode Fiber
- Commercial Temperature 0 to 70 Celsius
- Hot Pluggable
- Metal with Lower EMI
- Excellent ESD Protection
- RoHS Compliant and Lead Free



Applications:

- 10x Gigabit Ethernet over DWDM
- 8x/10x Fibre Channel
- Access, Metro and Enterprise

Product Description

This MSA compliant XFP transceiver provides 10GBase-DWDM throughput up to 100km over single-mode fiber (SMF) using a wavelength of 1546.12nm via an LC connector. It can operate at temperatures between 0 and 70C. All of our transceivers are built to comply with Multi-Source Agreement (MSA) standards and are uniquely serialized and tested for data-traffic and application to ensure seamless network integration. Additional product features include Digital Optical Monitoring (DOM) support which allows access to real-time operating parameters. This transceiver is Trade Agreements Act (TAA) compliant. We stand behind the quality of our products and proudly offer a limited lifetime warranty.

OptioConnect's transceivers are RoHS compliant and lead-free.

Regulatory Compliance

- ESD to the Electrical PINs: compatible with MIL-STD-883E Method 3015.4
- ESD to the LC Receptacle: compatible with IEC 61000-4-3
- EMI/EMC compatible with FCC Part 15 Subpart B Rules, EN55022:2010
- Laser Eye Safety compatible with FDA 21CFR, EN60950-1& EN (IEC) 60825-1,2
- RoHS compliant with EU RoHS 2.0 directive 2015/863/EU

Wavelength Guide (100GHz ITU-T Channel)

Channel #	Frequency (THz)	Center Wavelength (nm)
34	193.4	1550.12
35	193.5	1549.32
36	193.6	1548.51
37	193.7	1547.72
38	193.8	1546.92
39	193.9	1546.12
40	194.0	1545.32
41	194.1	1544.53
42	194.2	1543.73
43	194.3	1542.94
44	194.4	1542.14
45	194.5	1541.35
46	194.6	1540.56
47	194.7	1539.77
48	194.8	1538.98
49	194.9	1538.19
50	195.0	1537.40
51	195.1	1536.61
52	195.2	1535.82
53	195.3	1535.04
54	195.4	1534.25
55	195.5	1533.47
56	195.6	1532.68
57	195.7	1531.90
58	195.8	1531.12
59	195.9	1530.33
60	196.0	1529.55
61	196.1	1528.77

Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit
Maximum Supply Voltage	V _{cc3}	-0.5	3.6	V
	V _{cc5}	-0.5	6	V
Storage Temperature	T _S	-40	85	°C
Operating Temperature	T _O	0	70	°C
Operating Humidity	RH	5	95	%
Receiver power	R _{MAX}		-7	dBm
Maximum bitrate	B _{max}	9.95	11.3	Gbps

Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Power Supply Voltage	V _{cc3}	3.135	3.30	3.465	V	
	V _{cc5}	4.75	5.0	5.25	V	
Power Supply Current	I _{cc3}			750	mA	
Power Supply Current	I _{cc5}			500	mA	
Power Dissipation	P _D			3500	mW	
Transmitter						
Differential data input swing	V _{in,pp}	120		1000	mVp-p	
Input differential impedance	Z _{in}		100		Ω	
Tx_Disable, P_Down/RST	V _{IH}	2.0		V _{CC3} +0.3	V	
	V _{IL}	-0.3		0.8	V	
Transmit Disable Assert Time				10	us	
Receiver						
Differential data output swing	V _{out, pp}	340		850	mVp-p	1
Output differential impedance	Z _{in}		100		Ω	
Data Output Rise Time, Fall Time	t _r , t _f	24			ps	2
Rx_LOS, Mod_NR, Interrupt	V _{OH}	V _{CCHOST} -0.5		V _{CCHOST} +0.3	V	3
	V _{OL}	0		0.4	V	3

Notes:

1. Internally AC coupled but requires an external 100Ω differential termination.
2. 20–80%.
3. Loss of Signal is an open collector output. Should be pulled up with a 4.7kΩ-10kΩ resistor on the host board.

Optical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Transmitter						
Launch Average Optical Power	P _o	1		+4	dBm	1
Center Wavelength Range	λ _c	1528.77		1563.86	nm	
Center Wavelength Spacing			100		GHz	
Center Wavelength Tolerance	Δλ _c	-100		100	pm	
Extinction Ratio	EX	9			dB	2
Spectral Width (-20dB)	Δλ			0.3	nm	
Side Mode Suppression Ratio	SMSR	30			dB	
Average Optical Power (Laser Off)	P _{OFF}			-30	dBm	1
Eye Diagram	ITU-T G.691 SDH STM-64 L-64.2 compatible					2
Receiver						
Center Wavelength	λ _c	1528		1565	nm	
Receiver Sensitivity @ 9.953Gb/s	S			-26.0	dBm	3
Receiver Overload (P _{avg})	P _{OL}	-7.0			dBm	3
Optical Return Loss	ORL	27			dB	
LOS De-Assert	LOS _D			-27	dBm	
LOS Assert	LOS _A	-38			dBm	
LOS Hysteresis		0.5			dB	

Notes:

1. The optical power is launched into 9/125μm SMF.
2. Measured with a PRBS 2³¹-1 test pattern @ 9.953Gbps.
3. Measured with worst ER; 1550nm; PRBS 2³¹-1 test pattern @ 9.953Gb/s, BER<10⁻¹².

Pin Descriptions

Pin	Symbol	Name/Descriptions	Ref.
1	GND	Module Ground	
2	Vee5	(not required)	
3	MOD_DESEL	Module De-select; When Held low allows the module to respond to 2-wire serial interface. LVTTTL-I	
4	/INTERRUPT	Interrupt; Indicates presence of an important condition which can be read via the 2-wire serial interface. LVTTTL-O	2
5	TX_DIS	Transmitter Disable. Logic1 indicates laser output disabled, LVTTTL-I	
6	VCC5	+5V Power Supply (Not required)	
7	GND	Module Ground	1
8	VCC3	+3.3V Power Supply	
9	VCC3	+3.3V Power Supply	
10	SCL	2-Wire Serial Interface Clock. LVTTTL-I	2
11	SDA	2-Wire Serial Interface Data Line. LVTTTL-I/O	2
12	MOD_Abs	Indicates Module is not present. Grounded in the Module. LVTTTL-O	2
13	MOD_NR	Module Not Ready; Indicating Module Operational Fault. Open-collector. LVTTTL-O	2
14	RX_LOS	Loss of Signal indication. Logic 1 indicates loss of Signal. Open-collector. LVTTTL-O	2
15	GND	Module Ground	1
16	GND	Module Ground	1
17	RD-	Receiver Inverted Data Output. CML-O	
18	RD+	Receiver Non-Inverted Data Output. CML-O	
19	GND	Module Ground	1
20	VCC2	+1.8V Power Supply (Not required).	3
21	P_DOWN/RST	Power down; When high, requires the module to limit power consumption to 1.5W or below. 2-Wire serial interface must be functional in the low power mode. LVTTTL-I Reset; The falling edge initiates a complete reset of the module including the 2-wire serial interface, equivalent to a power cycle. LVTTTL-I	
22	VCC2	+1.8V Power Supply (Not required)	3
23	GND	Module Ground	1
24	REFCLK+	Reference Clock (Not required)	
25	REFCLK-	Reference Clock (Not required)	
26	GND	Module Ground	1
27	GND	Module Ground	1
28	TD-	Transmitter Inverted Data Input. CML-I	
29	TD+	Transmitter Non-Inverted Data Input. CML-I	
30	GND	Module Ground	1

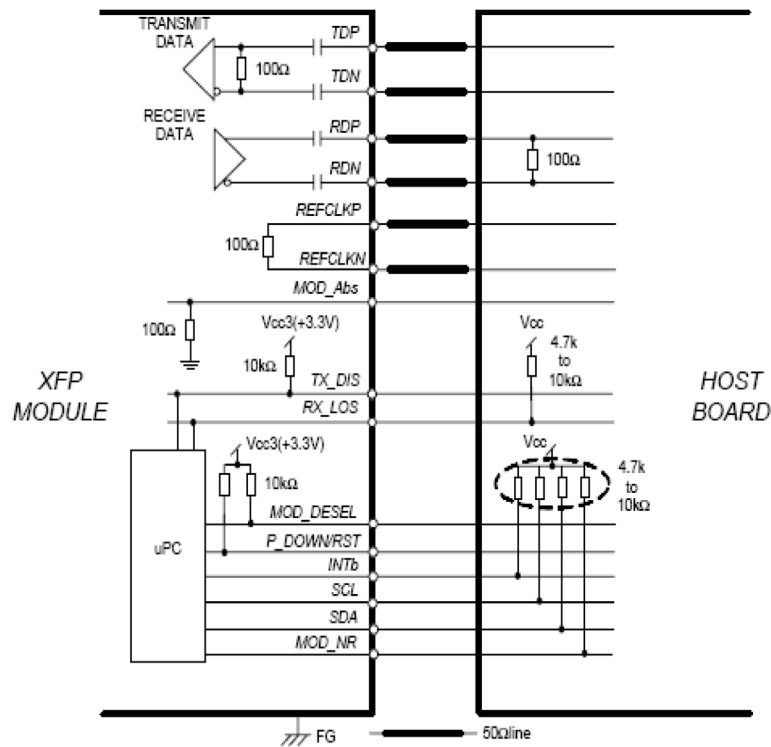
Notes:

1. Module ground pins GND are isolated from the module case and chassis ground within the module.
2. Open collector; should be pulled up with 4.7K-10Kohms to a voltage between 3.15V and 3.6V on the host board.
3. The pins are open within module.



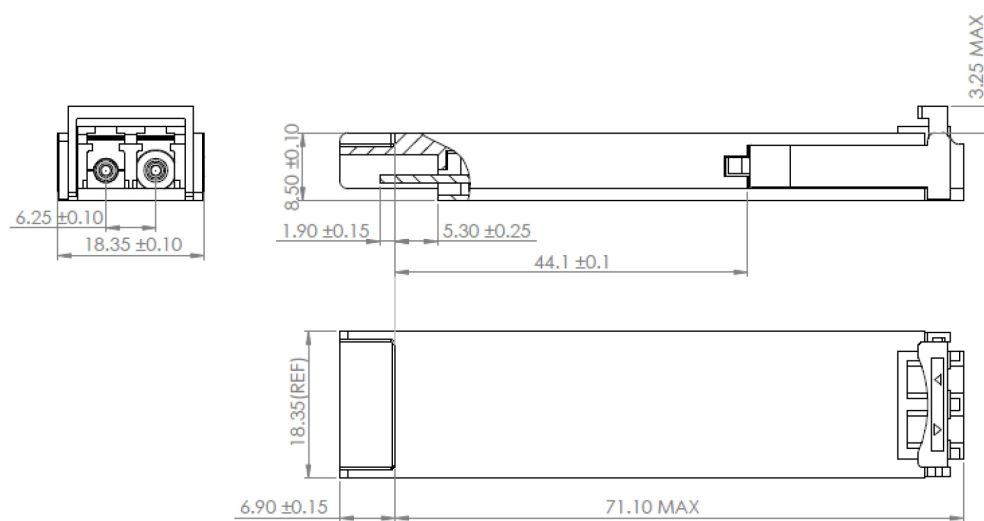
Pin-out of connector Block on Host board

Recommended Circuit Schematic



Mechanical Specifications

Small Form Factor Pluggable (XFP) transceivers are compatible with the dimensions defined by the XFP Multi-Sourcing Agreement (MSA).



EEPROM Information

Management Interface

XFP 2-wire serial interface is specified in the Chapter 4 of the XFP MSA specification. The XFP 2-wire serial interface is used for serial ID, digital diagnostics, and certain control functions. The 2-wire serial interface is mandatory for all XFP modules. The 2-wire serial interface address of the XFP module is 1010000X(A0h). In order to access to multiple modules on the same 2-wire serial bus, the XFP has a MOD_DESEL(module deselect pin). This pin (which is pull high or deselected in the module) must be held low by the host to select of interest and allow communication over 2-wire serial interface. The module must not respond to or accept 2-wire serial bus instructions unless it is selected.

XFP Management Interface

XFP Management interface is specified in the Chapter 5 of the XFP MSA specification. The Figure 1 shows the structure of the memory map. The normal 256 Byte address space is divided into lower and upper blocks of 128 Bytes. The lower block of 128 Byte is always directly available and is used for the diagnostics and control functions that must be accessed repeatedly. Multiple blocks of memories are available in the upper 128 Bytes of the address space. These are individually addressed through a table select Byte which the user enters into a location in the lower address space. The upper address space tables are used for less frequently accessed functions and control space for future standards definition.

EEPROM memory map specific data field description is as below:



OptioConnect

Innovation for the Future of High-Speed Networking

Who We Are

OptioConnect is reshaping the landscape of communication and high-speed networking through intelligent technology. With a core focus on cutting edge technology, we deliver smarter fiber optic solutions for enterprise networks, data centers, and next-gen telecom infrastructures.

What We Do

At OptioConnect, we fuse advanced engineering with intelligent automation to drive the future of networking. Our AI-integrated solutions are designed to optimize performance and streamline operations with:

- Superior Performance
- Network and traffic optimization
- Intelligent energy management
- Seamless OEM compatibility
- Scalable cost-efficiency

Smarter Networks by Design

Innovation isn't just a goal—it's our process. We embed AI and machine learning across our R&D and product lines, enabling adaptive performance, automated tuning, and faster deployment cycles. The result? Networks that don't just work—they learn, evolve, and outperform.

Our Team

Our engineers, data scientists, and network architects bring decades of experience and a future-focused mindset. We provide hands-on support with intelligent insights that turn complex challenges into simple solutions.

Our Mission

To deliver AI-enhanced connectivity that reduces cost, increases speed, and maximizes efficiency—empowering our partners to operate at the forefront of a rapidly evolving digital world.

Let's Connect

Discover how OptioConnect's intelligent infrastructure solutions can power your network's next leap forward.

www.optioconnect.com | info@optioconnect.com

